MOSFETs Silicon N-Channel MOS (π -MOSVIII)

TK7A90E



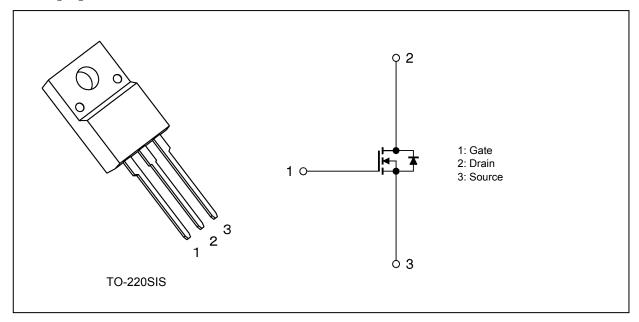
1. Applications

• Switching Voltage Regulators

2. Features

- (1) Low drain-source on-resistance: $R_{DS(ON)} = 1.6 \Omega$ (typ.)
- (2) Low leakage current : I_{DSS} = 10 μA (max) (V_{DS} = 720 V)
- (3) Enhancement mode: V_{th} = 2.5 to 4.0 V (V_{DS} = 10 V, I_D = 0.7 mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (T_a = 25 °C unless otherwise specified)

Characteristics			Rating	Unit	
Drain-source voltage		V_{DSS}	900	V	
Gate-source voltage		V _{GSS}	±30]	
Drain current (DC)	(Note 1)	I _D	7	Α	
Drain current (pulsed)	(Note 1)	I _{DP}	21		
Power dissipation (Ta	c = 25°C)	P _D	45	W	
Single-pulse avalanche energy	(Note 2)	E _{AS}	235	mJ	
Avalanche current		I _{AR}	7	Α	
Reverse drain current (DC)	(Note 1)	I _{DR}	7	1	
Reverse drain current (pulsed)	(Note 1)	I _{DRP}	21	1	
Channel temperature		T _{ch}	150	°C	
Storage temperature		T _{stg}	-55 to 150	1	
Isolation voltage (RMS)		V _{ISO(RMS)}	2000	V	
Mounting torque		TOR	0.6	N · m	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-case thermal resistance		2.78	°C/W
Channel-to-ambient thermal resistance	R _{th(ch-a)}	62.5	

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 8.8 mH, R_G = 25 Ω , I_{AR} = 7 A

6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±1	μА
Drain cut-off current	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	900	_	_	V
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 0.7 mA	2.5	_	4.0	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = 10 V, I _D = 3.5 A	_	1.6	2.0	Ω

6.2. Dynamic Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	1350	_	pF
Reverse transfer capacitance	C _{rss}		_	10		
Output capacitance	C _{oss}		_	110	_	
Gate resistance	r _g	V _{DS} = OPEN, f = 1 MHz	_	4.0	_	Ω
Switching time (rise time)	t _r	See Fig. 6.2.1.	_	20		ns
Switching time (turn-on time)	t _{on}		_	55	_	
Switching time (fall time)	t _f		_	15	_	
Switching time (turn-off time)	t _{off}]	_	85	_	
MOSFET dv/dt ruggedness	dv/dt	V _{DD} = 0 to 400 V, I _D = 7 A	20	_		V/ns

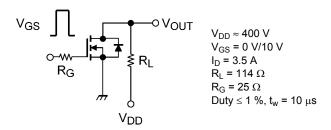


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}$	_	32	_	nC
Gate-source charge 1	Q _{gs1}		_	10	_	
Gate-drain charge	Q _{gd}		_	12	_	

6.4. Source-Drain Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage	V _{DSF}	I _{DR} = 7 A, V _{GS} = 0 V	_	_	-1.7	٧
Reverse recovery time	t _{rr}	I _{DR} = 7 A, V _{GS} = 0 V	_	1100	_	ns
Reverse recovery charge	Q _{rr}	-dI _{DR} /dt = 100 A/μs	_	8	_	μС
Peak reverse recovery current	I _{rr}		_	18	_	Α